

APPLICATION NOTE

MITSUBISHI<IGBT MODULE>

Tentative

CM400HA-24A

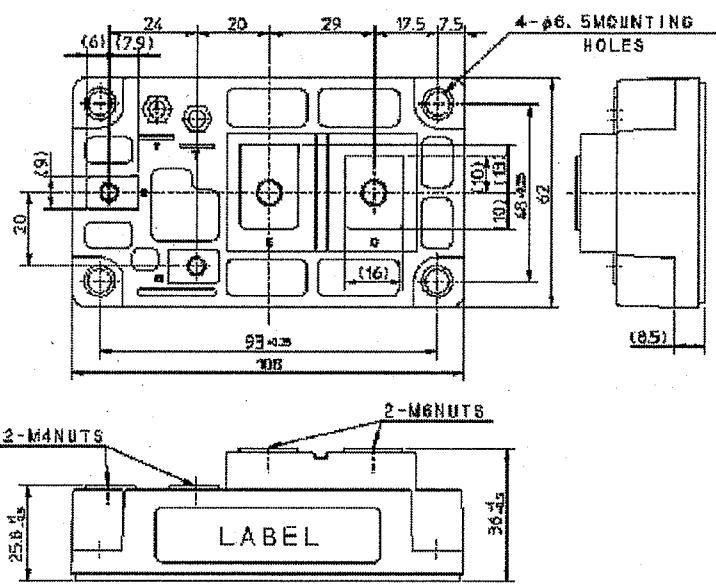
Pre.	H.Hanada	Rev	
Apr.	T.Funni 07-Oct-'03		

HIGH POWER SWITCHING USE

CM400HA-24A

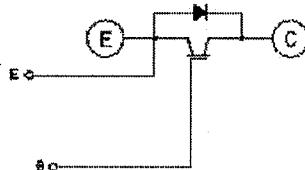
- I_c 400A
- V_{CES} 1200V
- Insulated Type
- 1-elements in a pack

OUTLINE DRAWING



Dimensions in mm

CIRCUIT DIAGRAM



APPLICATION

AC drive inverters & Servo controls,etc

ABSOLUTE MAXIMUM RATINGS ($T_j = 25^\circ\text{C}$)

Symbol	Item	Conditions	Ratings	Units
V_{GES}	Collector-emitter voltage	G-E Short	1200	V
V_{GES}	Gate-emitter voltage	C-E Short	± 20	V
I_c	Collector current	DC, $T_c = 87^\circ\text{C}$ *1	400	A
I_{CM}		Pulse ②	800	
I_E ①	Emitter current		400	A
I_{EM} ①		Pulse ②	800	
P_c ③	Maximum collector dissipation	$T_c = 25^\circ\text{C}$ *1	2710	W
T_j	Junction temperature		-40~+150	°C
T_{stg}	Storage temperature		-40~+125	°C
V_{iso}	Isolation voltage	Main terminal to base plate, AC 1 min.	2500	V
—	Torque strength	Main terminal M6	1.96 ~ 2.94	N·m
—	Torque strength	Mounting holes M6	1.96 ~ 2.94	N·m
—	Torque strength	G(E) terminal M4	0.98 ~ 1.47	N·m
—	Weight	Typical value	400	g

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HIGH POWER SWITCHING USE

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ\text{C}$)

Symbol	Item	Conditions		Min.	Typ.	Max.	Units
I_{CES}	Collector cutoff current	$V_{CE}=V_{CES}, V_{GE}= 0\text{V}$		—	—	1	mA
$V_{GE(\text{th})}$	Gate-emitter threshold voltage	$I_C=40\text{mA}, V_{CE}= 10\text{V}$		6	7	8	V
I_{GES}	Gate leakage current	$V_{GE}=V_{GES}, V_{CE}= 0\text{V}$		—	—	0.5	μA
$V_{CE(\text{sat})}$	Collector to emitter saturation voltage	$T_j = 25^\circ\text{C}$	$I_C = 400\text{A}$	—	2.1	3.0	V
		$T_j = 125^\circ\text{C}$	$V_{GE}= 15\text{V}$	—	2.4	—	
Cies	Input capacitance	$V_{CE}= 10\text{V}$		—	—	70	nF
Coes	Output capacitance	$V_{GE}= 0\text{V}$		—	—	6	
Cres	Reverse transfer capacitance			—	—	1.4	
Q_G	Total gate charge	$V_{CC}=600\text{V}, I_C=400\text{A}, V_{GE}=15\text{V}$		—	2000	—	nC
td(on)	Turn-on delay time	$V_{CC}=600\text{V}, I_C=400\text{A}$		—	—	550	ns
tr	Turn-on rise time	$V_{GE1}=V_{GE2}=15\text{V}$		—	—	180	
td(off)	Turn-off delay time	$R_G=0.78\Omega, \text{Inductive load}$		—	—	600	
tf	Turn-off fall time	switching operation		—	—	350	
trr ①	Reverse recovery time	$I_E=400\text{A}$		—	—	250	ns
Qrr ①	Reverse recovery charge			—	16	—	μC
V_{EC} ①	Emitter-collector voltage	$I_E=400\text{A}, V_{GE}= 0\text{V}$		—	—	3.8	V
Rth(j-c)Q	Thermal resistance	IGBT part *1		—	—	0.046	°C/W
		FWDi part *1		—	—	0.085	
Rth(c-f)	Contact thermal resistance	Case to fin, Thermal compound Applied *2		—	0.02	—	
R_G	External gate resistance			0.78	—	10	Ω

*1: T_c, T_f measured point is just under the chips.

*2: Typical value is measured by using Shin-etsu Silicone "G-746".

① $I_E, V_{EC}, \text{trr} \& Qrr$ represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWDi).

② Pulse width and repetition rate should be such that the device junction temp. (T_j) dose not exceed T_{jmax} rating.

③ Junction temperature (T_j) should not increase beyond 150°C .

④ Pulse width and repetition rate should be such as to cause neglible temperature rise.